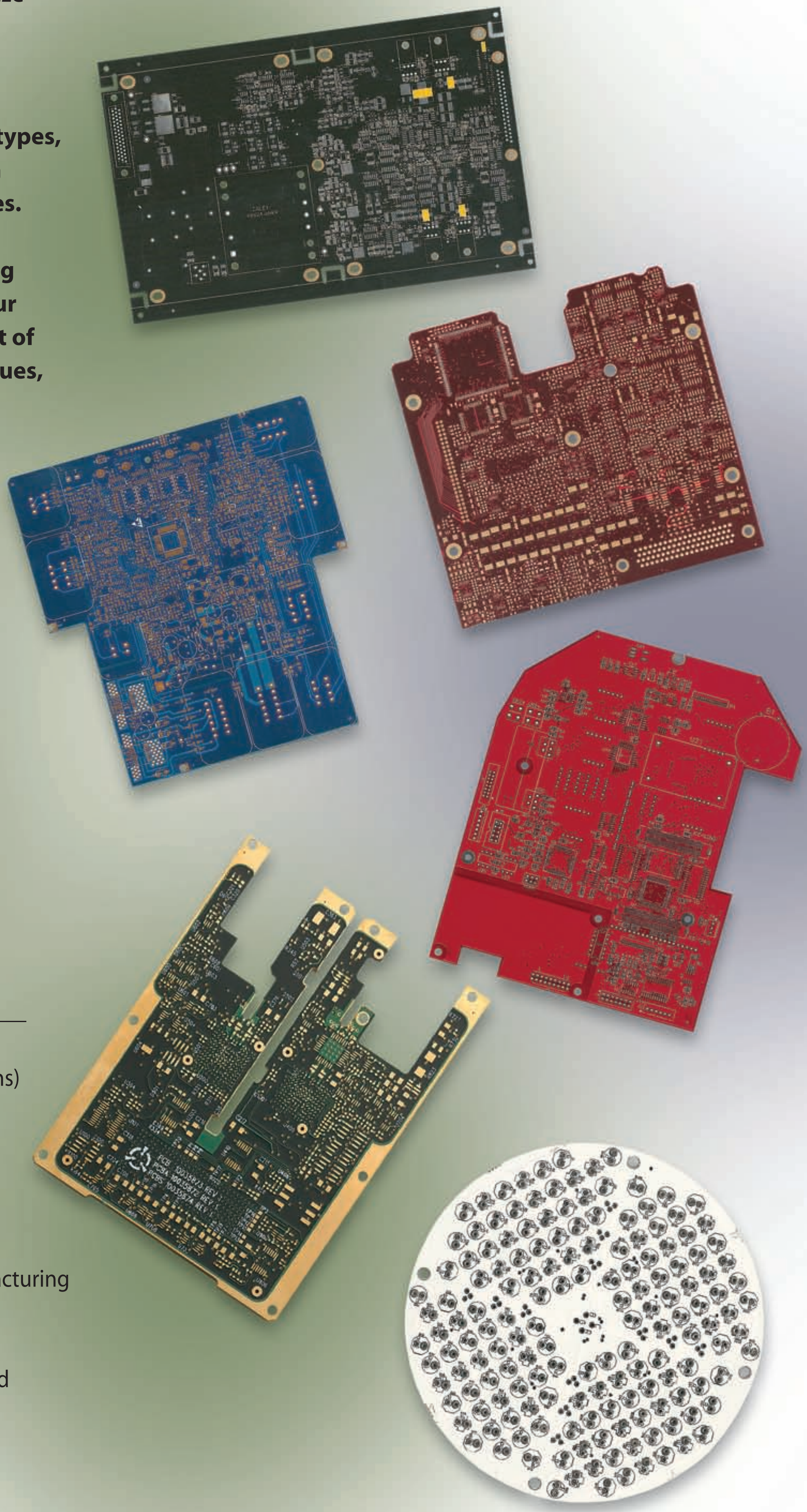
NetVia Group LLC

PCB Fabrication



NetVia Group, LLC is a one-stop source for quality printed circuit boards (PCBs). Prototypes, quick turns, low volume/high mix, and high volume are all within our proven capabilities.

But NetVia Group isn't just about fabricating boards, we're about partnerships. From your very first contact with us, through shipment of product, we're there to help with design issues, delivery requirements, and to provide high quality Printed Circuit Boards.

- ISO9001/2008 Certified
- IPC-6011, 6012, 6013 & 6018 Class 2 & 3
- MIL-PRF-55110
- UL 94V-0
- RoHS Compliant
- Quick Turn Protos - Down to 24 Hours
- Low Volume/High Mix
- LRIP to Medium Volume Production

Corp. Structure: Private, Small business (˜40 persons)
Corp. Headquarters: Irving, TX (DFW Metroplex)
CAGE CODE: 67370
DUNS: 113096655
TIN: 27-3610213
SIC: 3672, 3678
NAICS: 334412 Bare Printed Circuit Board Manufacturing
334418 Printed Circuit Board Assembly
(Electronic Assembly) Manufacturing
ITAR Registered, JCP Certified, CCR/SAM Registered

PaulOlson@NetViaGroup.com • 972-573-1392
netviagroup.com

Technology

DESCRIPTION	STANDARD	ADVANCED
LINE / SPACE		
Inner layer trace width / spacing (0.5 oz)	4/4	2.5/2.5
Inner layer trace width / spacing (1 oz)	5/5	3/4
Outer layer trace width / spacing (1 oz)	5/5	3/4
Outer layer trace width / spacing (2 oz)	8/8	6/6
MECHANICAL / TOLERANCE		
Aspect ratio	12:1	20:1
Minimum drill size (mechanical)	0.012″	0.006″
Minimum drill size (laser)	**0.005″**	**0.003″**
Minimum pad size over drill (outer layer)	0.010″	0.006″
Minimum pad size over drill (inner layer)	0.020″	0.010″
Blind vias available	Yes	Yes
Buried vias available	Yes	Yes
Cavity / pocket mill	**No**	**Yes**
Plated through hole size tolerance (+/- mils)	3	2
Drill position accuracy (+/- mils)	3	2
Layer count	12	38
Layer to layer registration (+/- mils)	5	3
Minimum core thickness	0.004″	0.002″
Minimum finished PCB thickness	0.020″	0.012″
Maximum finished PCB thickness	0.125″	0.500″
FINISHES		
HASL (hot air solder level) / 63% Tin / 37% Lead	Yes	Yes
HASL (hot air solder level) / Lead free / SN100CL	No	Yes
Electroless Nickel - 100u″ / Immersion Gold - 3u″ (ENIG)	Yes	Yes
Electroless Nickel - 100u″ / Immersion Gold - 5u″ (ENIG)	No	Yes
Electroless Nickel - 100u″ / Electroless Palladium - 8u″ Immersion Gold - 3u″ (ENEPIG)	Yes	Yes
Immersion Silver	Yes	Yes
Immersion Tin	Yes	Yes
OSP (Entek Cu106A)	No	Yes
Selective hard Gold plate up to 50u″	No	Yes
Carbon ink	No	Yes
VIP / non-conductive via fill (PP-2795 and PHP-900)	**Yes**	**Yes**
Conductive via fill (Tatsuta AE-3030)	**No**	**Yes**
LAMINATES		
FR4 - Tg 145 (IPC-4101/21)	Yes	Yes
FR4 - Tg 170 (IPC-4101/24 or /26)	Yes	Yes
FR4 - Tg 170+ for RoHS (IPC-4101/124)	Yes	Yes
Getek/FR408HR	Yes	Yes
RO4003/4350 (RO4000 series laminates)	Yes	Yes
Aluminum/Copper metal back	No	Yes
Polyimide	Yes	Yes
Telfon (RO5880, RO3006, RO6002, TLY, TLX)	Yes	Yes
Fastrise, 2929 bondply, 6700 bonding films	Yes	Yes
Flex	Yes	Yes
Rigid - Flex	No	Yes

- Advanced / unique technologies in red font -

Contact:
Paul Olson, *Business Development Manager*
PaulOlson@NetViaGroup.com
230 Irby Lane • Irving, Texas 75061
direct 972-573-1392 • cell 817-266-8833
netviagroup.com

NetVia Group LLC